



# Dell EMC PowerEdge R750xa Technical Specifications

## Thermal restriction matrix

Table 1. Label reference

LABEL	DESCRIPTION
STD	Standard
HPR	High performance
HSK	Heat sink
LP	Low profile
FH	Full height
DW	Double Wide (Xilinx FPGA accelerator)
BPS	Intel Persistent Memory 200 series (BPS)

Table 2. Processor and heat sink matrix

HEAT SINK	PROCESSOR TDP
2U HPR HSK	For all processor TDP

Table 3. Thermal restriction matrix

CONFIGURATION	MINIMUM	TYPICAL	MAXIMUM	AMBIENT TEMPERATURE
FRONT GPU TDP	70 W SW X 4	250 W DW X 4	300 W DW X 4	
FRONT DRIVES	X1 SAS/SATA	X8 SAS/SATA	X8 NVME	

CONFIGURATION		MINIMUM	TYPICAL	MAXIMUM	AMBIENT TEMPERATURE
FRONT GPU TDP		70 W SW X 4	250 W DW X 4	300 W DW X 4	
FRONT DRIVES		X1 SAS/SATA	X8 SAS/SATA	X8 NVME	
CPU TDP/cTDP	105 W	System Fan (60 x 76 mm) with 2U HPR HSK			35°C
	120 W				
	135 W				
	150 W				
	165 W				
	185 W				
	205 W				
	220 W				
	230 W				
	240 W				
	250 W				
	265 W				
	270 W				

**i** NOTE Six System fans (60 x 76 mm) are required for all the configurations.

**i** NOTE T4 GPU card is supported on riser 2 (R2a slot 3/6) with maximum power loading.

**i** NOTE Xeon(R) 8368Q supports only processor liquid cooling.

**i** NOTE Only ASHRAE A2 category ambient temperature is supported.

**i** NOTE For all memory configuration only System fan (60 x 76 mm) with 2U HPR HSK is used.

**i** NOTE BPS DIMMs supported only at 30°C ambient temperature.

**i** NOTE 128 GB LRDIMM, 64 GB RDIMM, 32 GB RDIMM, 16 GB RDIMM and 8 GB RDIMM supports at 35°C ambient temperature.